

4) 가
6) 가
TiN- nitride
50 GPa
7) 300% 가
가 가
가 가
가 가
가 가
가 가
(indentation size effect)가
Nix Gao

8) Berkovich
Nix Gao
가
Nix Gao
9) 가
가
가

100 nm
가
가
가
가
100 nm
가

2.
2.1 가
Fig. 1 가

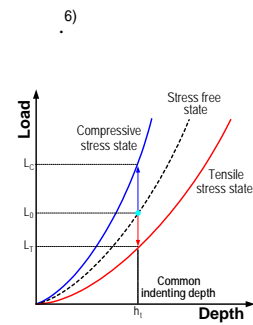


Fig. 1. Variation of the indentation loading curves with the changes in the stress states.

가 3
(hydrostatic stress)
2
3
1 가
Fig.
2 2 3
가

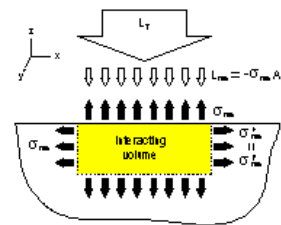


Fig. 2. Interaction of residual-stress-induced normal load(L_{res}) and indentation load(L_T).

Fig. 1 h_i

가 L_T L_0 L_c 가
 h_t
 L_c
 L_0 가
 L_{res} 가
 (L_T, h_t)
 (L_0, h_t) 가

(equivalent state)

$$L_0 = L_T + L_{res} \quad (1)$$

$$\sigma_{res} = L_{res} / A_c^0 \quad (2)$$

2.2

Fig. 3 (b)



Fig. 3. Schematic diagrams for (a) simple and (b) expanded rule-of-mixture.

H V_f
(rule-of-mixture)

$$H_c = H_{i0} V_{F,i0A} + H_{i0} V_{F,i0B} + H_{i,j} V_{F,i,j} \quad (3)$$

(3) A B
 (H_c) 가

2.3

Fig. 4

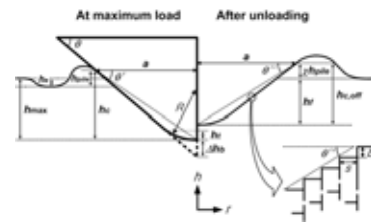


Fig. 4. Nanoindentation contact morphology including pile-up for a conical indenter with a blunt tip, and the distribution of geometrically necessary dislocations.

$$\rho_G = \frac{3\alpha}{2hc} \tan^2 \theta \quad (4)$$

b Burger's hc 가

von Mises 3 Tabor

$$H = 3\sigma = 3\sqrt{3\alpha\mu b} \sqrt{\rho_S + \rho_G} \quad (5)$$

μ 가 (4), (5)

$$\frac{H}{H_0} = \sqrt{1 + J \frac{h^*}{h_c}} \quad (6)$$

H_0 가

$$J = \chi \left(1 + \frac{\Delta h_b}{h_c} \right)^{-2} \quad (7)$$

3.

HYSITRON TriboScopeII
100 μ N/s
Berkovich

vickers

3.1

0.6 μ m E-beam evaporator 1.0 μ m Au

10

가

DLC

3.2

TiN/VN, TiN/NbN, CrN/NbN 3가 UBM
(Unbalanced Magnetron) Si(100)
epitaxial
 10^{-6} Torr 8
mTorr R.F. 250, 120
sccm

3.3

99.99%

AFM

, Poisson ,

4.

4.1

(diamond-like carbon) Au
Fig. 5

- 가
- 가

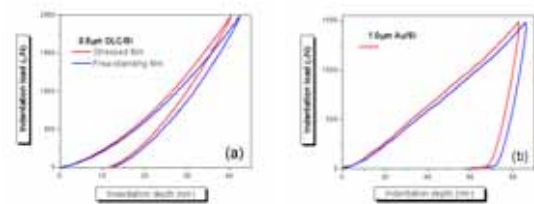


Fig. 5. Comparisons of the analyzed residual stress values for (a) DLC/Si and (b) Au/Si by the effect of thin film residual stress.

Au

-3.8 ± 0.5 GPa

-93.4 ± 28.5 MPa

가

가

가

5%

가

Au

-3.75 GPa -104.8 MPa

10

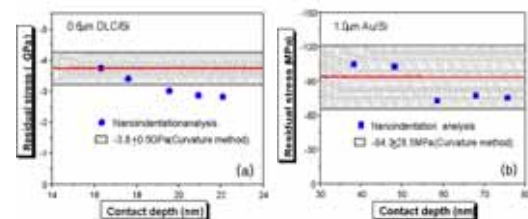


Fig. 6. Comparisons of the analyzed residual stress values for (a) DLC/Si and (b) Au/Si with the results from curvature method.

4.2

3가

가

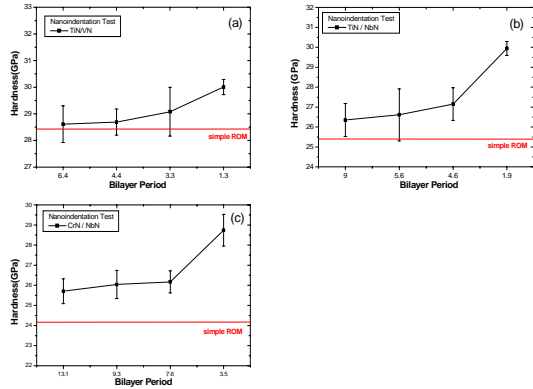


Fig. 7. Hardness data of 3 multilayer systems for the different bilayer periods: (a) TiN/VN, (b) TiN/NbN, and (c) CrN/NbN.

가

가

가

가 가 13) 가

(3)

가

(3)

1

가

(iteration) 4

가

, HI

, w

Table 2

Table 2 Interface hardness and thickness for TiN/VN, TiN/NbN, and CrN/NbN systems

	TiN/VN	TiN/NbN	CrN/NbN
H_0 (GPa)	47.78	53.04	48.94
w (nm)	0.212	0.330	0.654

가
가

50 GPa

가

Fig. 8

가

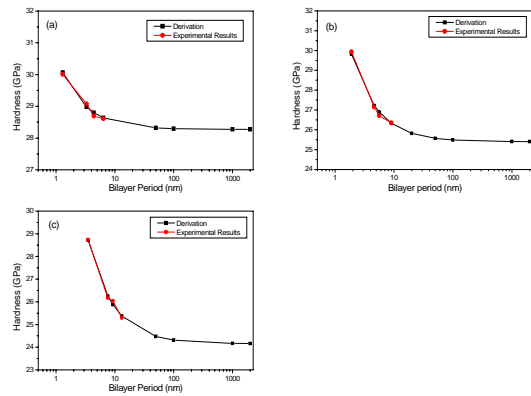


Fig. 8. Transition of hardness values for bilayer periods: (a) TiN/VN, (b) TiN/NbN, and (c) CrN/NbN

4.3

Fig. 9 A, B

A, B

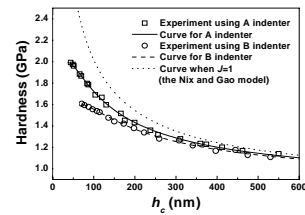


Fig. 9. Hardness results with contact depth and curves fitted by the present model for annealed Cu using A and B indenters.

H_0 h' A
0.846 GPa, 463 nm , B
0.842 GPa, 472 nm

가 H_0 h' 가 가

가 A H_0 h' 0.798 GPa, 538 nm , B 0.820 GPa, 505 nm

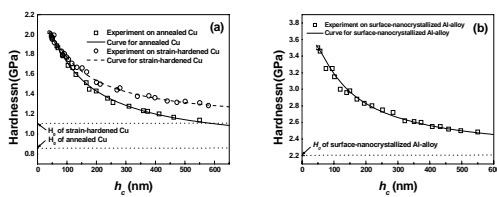


Fig. 10. Hardness results with contact depth and curves fitted by the present model for (a) annealed and strain-hardened Cu, and (b) surface-nanocrystallized Al-alloy.

Fig. 10 A

가 J A

가 5.

1. Au 가

2. 가

3.

21

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